B/O FORM PTO 1595 (1/31/92) Patent and Trademark Office RECORDATION FORM COVER SHEET

08-28-2001





To the Honorab	ole Commissioner of Patents and Trademarks. Please reco	rd the attached original documents or copy thereof.
 Name of Conveying Party(ies): Masatoshi MORIKAWA, (2) Mio SHINDO, (3) Isao YOSHIDA and (4) Kenichi NAGURA Additional names of conveying parties attached 		Name and Address of Receiving Party(ies): Name: Hitachi, Ltd. Internal Address:
✓ As☐ Sec☐ Ot	re of Conveyance: signment	Street Address: 6, Kanda Surugadai 4-chome City, State, Zip: Chiyoda-ku, Tokyo, Japan
If this documen execution dates :	tent Application Number(s): t is being filed together with a new application, the of the application are: (1) June 7, 2001 (2) (3) June 11, 2001 (4) June 8, 2001	4. (b) Patent Numbers:
	and Address of Party to whom Correspondence erning this Document Should be Mailed:	6. Total Number of Applications and Patents Involved: 1
Name:	Stanley P. Fisher	7. Total Fee: \$40.00 (37 C.F.R. § 3.41)
Address:	Reed Smith Hazel Thomas LLP 3110 Fairview Park Dr. Suite 1400 Falls Church, Va. 22042	 ≅ Enclosed. ☐ Authorized to be charged to deposit account. 8. Deposit Account Number:
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9. Staten	nent and Signature:	
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/	f pages comprising cover sheet: 1	Committee of the commit

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PATENT REEL: 012098 FRAME: 0792

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6. Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner-ship of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INIVENITORIOS

RECORDED: 08/15/2001

(発明者フルネームサイン)	(署名日)
1) Martoshi Marikawa (Masatoshi MORIKAWA)	7/ June /200/
2) Mio Shindo (Mio SHINDO)	11/ June / 2001
3) Isao yoshida (Isao YOSHIDA)	11/June/2001
4) Kenichi Nagura (Kenichi NAGURA)	8/ June / 2001
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PATENT REEL: 012098 FRAME: 0793

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